


MATERIAL DECLARATION SHEET

Package Type	PTVS6-xxxC-M			
Product Line	Semiconductor products			
Compliance Date	20 th Jan 2017			
RoHS Compliant	Yes	MSL	Level 1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy resin	2.1646	Amorphous Silica	60676-86-0	89.50	50.34	56.25
				Solid Epoxy Resin 1	Proprietary	3.20	1.80	
				Solid Epoxy Resin 2	Proprietary	2.40	1.35	
				Phenol Resin	Proprietary	4.10	2.31	
				Crystalline Silica	14808-60-7	0.50	0.28	
				Carbon Black	1333-86-4	0.30	0.17	
2	Leadframe	Copper Alloy	0.5920	Copper	7440-50-8	97.44	14.99	15.38
				Iron	7439-89-6	2.35	0.36	
				Other, not to declare	-	0.21	0.03	
3	Electrodes	Copper Alloy	0.6988	Copper	7440-50-8	99.50	18.07	18.16
				Other, not to declare	-	0.50	0.09	
4	Clip	Copper Alloy	0.1181	Copper	7440-50-8	99.50	3.05	3.07
				Other, not to declare	-	0.50	0.02	
5	Chip	Silicon	0.1397	Silicon	7440-21-3	89.01	3.23	3.63
				Aluminum	7429-90-5	4.19	0.15	
				Nickel	7440-02-0	6.49	0.24	
				Gold	7440-57-5	0.31	0.01	
6	Die Attach	Solder	0.1138	Lead*	7439-92-1	92.50	2.74	2.96
				Tin	7440-31-5	5.00	0.15	
				Silver	7440-22-4	2.50	0.07	
7	Terminal Finish	Tin	0.0213	Tin	7440-31-5	100.00	0.55	0.55
			Total Weight	3.8483				

* 7(a) Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)